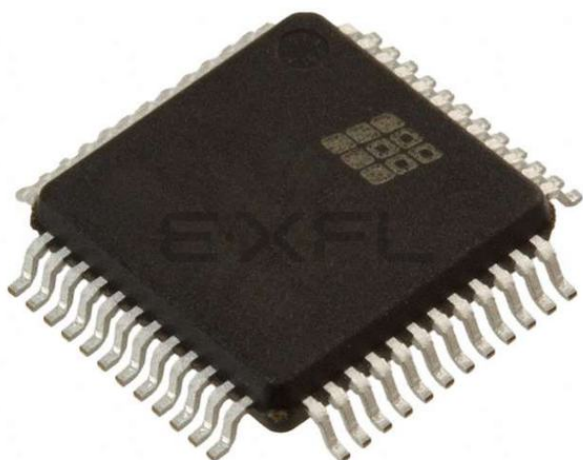




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	1.65V ~ 1.95V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	-
Number of I/O	32
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4064c-5t48c

Table 2. ispMACH 4000Z Family Selection Guide

	ispMACH 4032ZC	ispMACH 4064ZC	ispMACH 4128ZC	ispMACH 4256ZC
Macrocells	32	64	128	256
I/O + Dedicated Inputs	32+4/32+4	32+4/32+12/ 64+10/64+10	64+10/96+4	64+10/96+6/ 128+4
t _{PD} (ns)	3.5	3.7	4.2	4.5
t _S (ns)	2.2	2.5	2.7	2.9
t _{CO} (ns)	3.0	3.2	3.5	3.8
f _{MAX} (MHz)	267	250	220	200
Supply Voltage (V)	1.8	1.8	1.8	1.8
Max. Standby I _{CC} (μA)	20	25	35	55
Pins/Package	48 TQFP 56 csBGA	48 TQFP 56 csBGA 100 TQFP 132 csBGA	100 TQFP 132csBGA	100 TQFP 132 csBGA 176 TQFP

ispMACH 4000 Introduction

The high performance ispMACH 4000 family from Lattice offers a SuperFAST CPLD solution. The family is a blend of Lattice's two most popular architectures: the ispLSI® 2000 and ispMACH 4A. Retaining the best of both families, the ispMACH 4000 architecture focuses on significant innovations to combine the highest performance with low power in a flexible CPLD family.

The ispMACH 4000 combines high speed and low power with the flexibility needed for ease of design. With its robust Global Routing Pool and Output Routing Pool, this family delivers excellent First-Time-Fit, timing predictability, routing, pin-out retention and density migration.

The ispMACH 4000 family offers densities ranging from 32 to 512 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP), Chip Scale BGA (csBGA) and Fine Pitch Thin BGA (ftBGA) packages ranging from 44 to 256 pins/balls. Table 1 shows the macrocell, package and I/O options, along with other key parameters.

The ispMACH 4000 family has enhanced system integration capabilities. It supports 3.3V (4000V), 2.5V (4000B) and 1.8V (4000C/Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The ispMACH 4000 also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The ispMACH 4000 family members are 3.3V/2.5V/1.8V in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to V_{CC} (logic core).

Overview

The ispMACH 4000 devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

Absolute Maximum Ratings^{1, 2, 3}

	ispMACH 4000C/Z (1.8V)	ispMACH 4000B (2.5V)	ispMACH 4000V (3.3V)
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V	-0.5 to 4.5V
Input or I/O Tristate Voltage Applied ^{4, 5}	-0.5 to 5.5V	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C	-65 to 150°C
Junction Temperature (T_j) with Power Applied	-55 to 150°C	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Undershoot of -2V and overshoot of (V_{IH} (MAX) + 2V), up to a total pin voltage of 6.0V, is permitted for a duration of < 20ns.
5. Maximum of 64 I/Os per device with $V_{IN} > 3.6V$ is allowed.

Recommended Operating Conditions

Symbol	Parameter		Min.	Max.	Units
V _{CC}	Supply Voltage for 1.8V Devices	ispMACH 4000C	1.65	1.95	V
		ispMACH 4000Z	1.7	1.9	V
		ispMACH 4000Z, Extended Functional Voltage Operation	1.6 ^{1, 2}	1.9	V
	Supply Voltage for 2.5V Devices		2.3	2.7	V
	Supply Voltage for 3.3V Devices		3.0	3.6	V
T _j	Junction Temperature (Commercial)		0	90	C
	Junction Temperature (Industrial)		-40	105	C
	Junction Temperature (Extended)		-40	130	C

1. Devices operating at 1.6V can expect performance degradation up to 35%.
2. Applicable for devices with 2004 date codes and later. Contact factory for ordering instructions.

Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle	1,000	—	Cycles

Note: Valid over commercial temperature range.

Hot Socketing Characteristics^{1,2,3}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	$0 \leq V_{IN} \leq 3.0V$, $T_j = 105^\circ C$	—	± 30	± 150	μA
		$0 \leq V_{IN} \leq 3.0V$, $T_j = 130^\circ C$	—	± 30	± 200	μA

1. Insensitive to sequence of V_{CC} or V_{CCO} . However, assumes monotonic rise/fall rates for V_{CC} and V_{CCO} , provided $(V_{IN} - V_{CCO}) \leq 3.6V$.
2. $0 < V_{CC} < V_{CC} (MAX)$, $0 < V_{CCO} < V_{CCO} (MAX)$.
3. I_{DK} is additive to I_{PU} , I_{PD} or I_{BH} . Device defaults to pull-up until fuse circuitry is active.

Supply Current, ispMACH 4000V/B/C (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{CC}^{4}	Standby Power Supply Current	$V_{CC} = 3.3V$	—	13	—	mA
		$V_{CC} = 2.5V$	—	13	—	mA
		$V_{CC} = 1.8V$	—	3	—	mA

1. $T_A = 25^{\circ}C$, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I_{CC} varies with specific device configuration and operating frequency.
4. $T_A = 25^{\circ}C$

Supply Current, ispMACH 4000Z

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	50	—	μA
		Vcc = 1.9V, T _A = 70°C	—	58	—	μA
		Vcc = 1.9V, T _A = 85°C	—	60	—	μA
		Vcc = 1.9V, T _A = 125°C	—	70	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	10	—	μA
		Vcc = 1.9V, T _A = 70°C	—	13	20	μA
		Vcc = 1.9V, T _A = 85°C	—	15	25	μA
		Vcc = 1.9V, T _A = 125°C	—	22	—	μA
ispMACH 4064ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	80	—	μA
		Vcc = 1.9V, T _A = 70°C	—	89	—	μA
		Vcc = 1.9V, T _A = 85°C	—	92	—	μA
		Vcc = 1.9V, T _A = 125°C	—	109	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	11	—	μA
		Vcc = 1.9V, T _A = 70°C	—	15	25	μA
		Vcc = 1.9V, T _A = 85°C	—	18	35	μA
		Vcc = 1.9V, T _A = 125°C	—	37	—	μA
ispMACH 4128ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	168	—	μA
		Vcc = 1.9V, T _A = 70°C	—	190	—	μA
		Vcc = 1.9V, T _A = 85°C	—	195	—	μA
		Vcc = 1.9V, T _A = 125°C	—	212	—	μA
ICC ^{4, 5}	Standby Power Supply Current	Vcc = 1.8V, T _A = 25°C	—	12	—	μA
		Vcc = 1.9V, T _A = 70°C	—	16	35	μA
		Vcc = 1.9V, T _A = 85°C	—	19	50	μA
		Vcc = 1.9V, T _A = 125°C	—	42	—	μA

ispMACH 4000V/B/C Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-2.5		-2.7		-3		-3.5		Units
In/Out Delays										
t _{IN}	Input Buffer Delay	—	0.60	—	0.60	—	0.70	—	0.70	ns
t _{GOE}	Global OE Pin Delay	—	2.04	—	2.54	—	3.04	—	3.54	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	0.78	—	1.28	—	1.28	—	1.28	ns
t _{BUF}	Delay through Output Buffer	—	0.85	—	0.85	—	0.85	—	0.85	ns
t _{EN}	Output Enable Time	—	0.96	—	0.96	—	0.96	—	0.96	ns
t _{DIS}	Output Disable Time	—	0.96	—	0.96	—	0.96	—	0.96	ns
Routing/GLB Delays										
t _{ROUTE}	Delay through GRP	—	0.61	—	0.81	—	1.01	—	1.01	ns
t _{MCELL}	Macrocell Delay	—	0.45	—	0.55	—	0.55	—	0.65	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	0.11	—	0.31	—	0.31	—	0.31	ns
t _{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	—	0.00	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	0.44	—	0.44	—	0.44	—	0.94	ns
t _{PDi}	Macrocell Propagation Delay	—	0.64	—	0.64	—	0.64	—	0.94	ns
Register/Latch Delays										
t _S	D-Register Setup Time (Global Clock)	0.92	—	1.12	—	1.02	—	0.92	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32	—	1.32	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.12	—	1.32	—	1.22	—	1.12	—	ns
t _{ST_PT}	T-Register Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32	—	1.32	—	ns
t _H	D-Register Hold Time	0.88	—	0.68	—	0.98	—	1.08	—	ns
t _{HT}	T-Register Hold Time	0.88	—	0.68	—	0.98	—	1.08	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	0.82	—	1.37	—	1.27	—	1.27	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	0.88	—	0.63	—	0.73	—	0.73	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.88	—	0.63	—	0.73	—	0.73	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.52	—	0.52	—	0.52	ns
t _{CES}	Clock Enable Setup Time	2.25	—	2.25	—	2.25	—	2.25	—	ns
t _{CEH}	Clock Enable Hold Time	1.88	—	1.88	—	1.88	—	1.88	—	ns
t _{SL}	Latch Setup Time (Global Clock)	0.92	—	1.12	—	1.02	—	0.92	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32	—	1.32	—	ns
t _{HL}	Latch Hold Time	1.17	—	1.17	—	1.17	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	—	0.33	ns

ispMACH 4000V/B/C Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.50	—	2.00	ns
t _{GOE}	Global OE Pin Delay	—	4.04	—	6.04	—	7.04	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.83	—	2.28	—	3.28	ns
t _{BUF}	Delay through Output Buffer	—	1.00	—	1.50	—	1.50	ns
t _{EN}	Output Enable Time	—	0.96	—	0.96	—	0.96	ns
t _{DIS}	Output Disable Time	—	0.96	—	0.96	—	0.96	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	1.51	—	2.26	—	3.26	ns
t _{MCELL}	Macrocell Delay	—	1.05	—	1.45	—	1.95	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	0.56	—	0.96	—	1.46	ns
t _{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	1.54	—	2.24	—	3.24	ns
t _{PDi}	Macrocell Propagation Delay	—	0.94	—	1.24	—	1.74	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.52	—	1.77	—	1.77	—	ns
t _{ST_PT}	T-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _H	D-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{HT}	T-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.52	—	1.57	—	1.57	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	0.68	—	1.18	—	1.18	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.68	—	1.18	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.67	—	1.17	ns
t _{CES}	Clock Enable Setup Time	2.25	—	2.25	—	2.25	—	ns
t _{CEH}	Clock Enable Hold Time	1.88	—	1.88	—	1.88	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{HL}	Latch Hold Time	1.17	—	1.17	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	ns
t _{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	0.62	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	2.51	—	3.41	—	3.41	ns

ispMACH 4000Z Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GPTOE}	Global PT OE Delay	—	1.9	—	2.35	—	2.60	ns
t _{PPTOE}	Macrocell PT OE Delay	—	2.4	—	3.35	—	2.60	ns

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the timing model in this data sheet for further details.

Timing v.2.2

ispMACH 4000V/B/C Timing Adders¹

Adder Type	Base Parameter	Description	-25		-27		-3		-35		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders											
t _{INDIO}	t _{INREG}	Input register delay	—	0.95	—	1.00	—	1.00	—	1.00	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	—	0.33	ns
t _{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	—	0.05	ns
t _{BLA}	t _{ROUTE}	Additional block loading adder	—	0.03	—	0.05	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters											
LVTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTL standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters											
LVTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

ispMACH 4000Z Timing Adders ¹

Adder Type	Base Parameter	Description	-35		-37		-42		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t _{INDIO}	t _{INREG}	Input register delay	—	1.00	—	1.00	—	1.30	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.40	—	0.40	—	0.45	ns
t _{ORP}	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t _{BLA}	t _{ROUTE}	Additional block load-ing adder	—	0.04	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters									
LVTTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters									
LVTTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding the use of these adders.

ispMACH 4000Z Timing Adders (Cont.)¹

Adder Type	Base Parameter	Description	-45		-5		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t _{INDIO}	t _{INREG}	Input register delay	—	1.30	—	1.30	—	1.30	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.45	—	0.45	—	0.50	ns
t _{ORP}	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t _{BLA}	t _{ROUTE}	Additional block load- ing adder	—	0.05	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters									
LVTTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters									
LVTTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

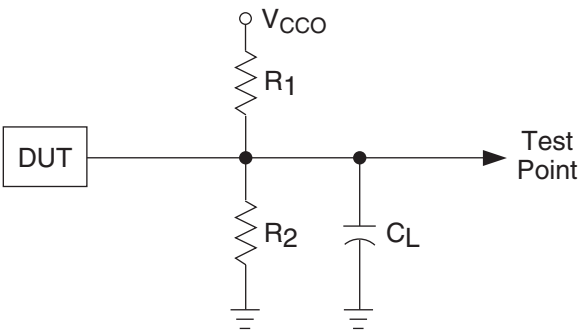
Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

Switching Test Conditions

Figure 12 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 11.

Figure 12. Output Test Load, LVTTTL and LVCMOS Standards



0213A/ispm4k

Table 11. Test Fixture Required Components

Test Condition	R_1	R_2	C_L^1	Timing Ref.	V_{CCO}
LVCMOS I/O, (L -> H, H -> L)	106 Ω	106 Ω	35pF	LVCMOS 3.3 = 1.5V	LVCMOS 3.3 = 3.0V
				LVCMOS 2.5 = $V_{CCO}/2$	LVCMOS 2.5 = 2.3V
				LVCMOS 1.8 = $V_{CCO}/2$	LVCMOS 1.8 = 1.65V
LVCMOS I/O (Z -> H)	∞	106 Ω	35pF	1.5V	3.0V
LVCMOS I/O (Z -> L)	106 Ω	∞	35pF	1.5V	3.0V
LVCMOS I/O (H -> Z)	∞	106 Ω	5pF	$V_{OH} - 0.3$	3.0V
LVCMOS I/O (L -> Z)	106 Ω	∞	5pF	$V_{OL} + 0.3$	3.0V

1. C_L includes test fixtures and probe capacitance.

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
86	1	F12	F ⁹	L8	L ⁴
87	1	F13	F ¹⁰	L6	L ³
88	1	F14	F ¹¹	L4	L ²
89	1	NC ²	-	I ²	-
90	1	GND (Bank 1) ¹	-	NC ¹	-
91	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
92	1	NC ²	-	I ²	-
93	1	G14	G ¹¹	M2	M ¹
94	1	G13	G ¹⁰	M4	M ²
95	1	G12	G ⁹	M6	M ³
96	1	G10	G ⁸	M8	M ⁴
97	1	G9	G ⁷	M10	M ⁵
98	1	G8	G ⁶	M12	M ⁶
99	1	GND (Bank 1)	-	GND (Bank 1)	-
100	1	G6	G ⁵	N2	N ¹
101	1	G5	G ⁴	N4	N ²
102	1	G4	G ³	N6	N ³
103	1	G2	G ²	N8	N ⁴
104	1	G1	G ¹	N10	N ⁵
105	1	G0	G ⁰	N12	N ⁶
106	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
107	-	TDO	-	TDO	-
108	-	VCC	-	VCC	-
109	-	GND	-	GND	-
110	1	NC ²	-	I ²	-
111	1	H14	H ¹¹	O12	O ⁶
112	1	H13	H ¹⁰	O10	O ⁵
113	1	H12	H ⁹	O8	O ⁴
114	1	H10	H ⁸	O6	O ³
115	1	H9	H ⁷	O4	O ²
116	1	H8	H ⁶	O2	O ¹
117	1	NC ²	-	I ²	-
118	1	GND (Bank 1)	-	GND (Bank 1)	-
119	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
120	1	H6	H ⁵	P12	P ⁶
121	1	H5	H ⁴	P10	P ⁵
122	1	H4	H ³	P8	P ⁴
123	1	H2	H ²	P6	P ³
124	1	H1	H ¹	P4	P ²
125	1	H0/GOE1	H ⁰	P2/GOE1	P ¹
126	1	CLK3/I	-	CLK3/I	-
127	0	GND (Bank 0)	-	GND (Bank 0)	-
128	0	CLK0/I	-	CLK0/I	-

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
129	-	VCC	-	VCC	-
130	0	A0/GOE0	A^0	A2/GOE0	A^1
131	0	A1	A^1	A4	A^2
132	0	A2	A^2	A6	A^3
133	0	A4	A^3	A8	A^4
134	0	A5	A^4	A10	A^5
135	0	A6	A^5	A12	A^6
136	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
137	0	GND (Bank 0)	-	GND (Bank 0)	-
138	0	A8	A^6	B2	B^1
139	0	A9	A^7	B4	B^2
140	0	A10	A^8	B6	B^3
141	0	A12	A^9	B8	B^4
142	0	A13	A^10	B10	B^5
143	0	A14	A^11	B12	B^6
144	0	NC ²	-	I ²	-

1. For device migration considerations, these NC pins are GND pins for I/O banks in ispMACH 4128V devices.

2. For device migration considerations, these NC pins are input signal pins in ispMACH 4256V devices.

ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections: 176-Pin TQFP

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	NC	-	NC	-	NC	-
2	-	GND	-	GND	-	GND	-
3	-	TDI	-	TDI	-	TDI	-
4	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
5	0	C14	C^7	C14	C^7	C14	C^7
6	0	C12	C^6	C12	C^6	C12	C^6
7	0	C10	C^5	C10	C^5	C10	C^5
8	0	C8	C^4	C8	C^4	C8	C^4
9	0	C6	C^3	C6	C^3	C6	C^3
10	0	C4	C^2	C4	C^2	C4	C^2
11	0	C2	C^1	C2	C^1	C2	C^1
12	0	C0	C^0	C0	C^0	C0	C^0
13	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
14	0	D14	D^7	E14	E^7	G14	G^7
15	0	D12	D^6	E12	E^6	G12	G^6
16	0	D10	D^5	E10	E^5	G10	G^5
17	0	D8	D^4	E8	E^4	G8	G^4
18	0	D6	D^3	E6	E^3	G6	G^3

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C ⁷	C14	C ⁹	C14	C ⁷	C14	C ⁷
F5	0	C12	C ⁶	C12	C ⁸	C12	C ⁶	C12	C ⁶
D3	0	C10	C ⁵	C10	C ⁷	C10	C ⁵	C10	C ⁵
C1	0	C8	C ⁴	C9	C ⁶	C8	C ⁴	C8	C ⁴
C2	0	C6	C ³	C8	C ⁵	C6	C ³	C6	C ³
E3	0	C4	C ²	C6	C ⁴	C4	C ²	C4	C ²
D2	0	C2	C ¹	C4	C ³	C2	C ¹	C2	C ¹
F6	0	C0	C ⁰	C2	C ²	C0	C ⁰	C0	C ⁰
D1	0	NC	-	C1	C ¹	F6	F ³	H0	H ⁰
E2	0	NC	-	C0	C ⁰	F4	F ²	H4	H ¹
E4	0	NC	-	NC	-	D6	D ³	F4	F ²
G5	0	NC	-	NC	-	D4	D ²	F6	F ³
E1	0	NC	-	NC	-	NC	-	F8	F ⁴
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F ⁵
F1	0	NC	-	NC	-	D2	D ¹	F12	F ⁶
G1	0	NC	-	NC	-	D0	D ⁰	F14	F ⁷
G6	0	NC	-	D14	D ⁹	F2	F ¹	H8	H ²
G4	0	NC	-	D12	D ⁸	F0	F ⁰	H12	H ³
H6	0	D14	D ⁷	D10	D ⁷	E14	E ⁷	G14	G ⁷
G3	0	D12	D ⁶	D9	D ⁶	E12	E ⁶	G12	G ⁶
H5	0	D10	D ⁵	D8	D ⁵	E10	E ⁵	G10	G ⁵
G2	0	D8	D ⁴	D6	D ⁴	E8	E ⁴	G8	G ⁴
H1	0	D6	D ³	D4	D ³	E6	E ³	G6	G ³
H2	0	D4	D ²	D2	D ²	E4	E ²	G4	G ²
H3	0	D2	D ¹	D1	D ¹	E2	E ¹	G2	G ¹
H4	0	D0	D ⁰	D0	D ⁰	E0	E ⁰	G0	G ⁰
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E ⁰	E0	E ⁰	H0	H ⁰	J0	J ⁰
J3	0	E2	E ¹	E1	E ¹	H2	H ¹	J2	J ¹
J2	0	E4	E ²	E2	E ²	H4	H ²	J4	J ²
J1	0	E6	E ³	E4	E ³	H6	H ³	J6	J ³
K1	0	E8	E ⁴	E6	E ⁴	H8	H ⁴	J8	J ⁴
J5	0	E10	E ⁵	E8	E ⁵	H10	H ⁵	J10	J ⁵
K2	0	E12	E ⁶	E9	E ⁶	H12	H ⁶	J12	J ⁶

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
J6	0	E14	E ⁷	E10	E ⁷	H14	H ⁷	J14	J ⁷
K3	0	NC	-	E12	E ⁸	G0	G ⁰	I0	I ⁰
K4	0	NC	-	E14	E ⁹	G2	G ¹	I4	I ¹
L1	0	NC	-	NC	-	I14	I ⁷	K0	K ⁰
L2	0	NC	-	NC	-	I12	I ⁶	K2	K ¹
M1	0	NC	-	NC	-	NC	-	K4	K ²
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
M2	0	NC	-	NC	-	NC	-	K6	K ³
N1	0	NC	-	NC	-	I10	I ⁵	K8	K ⁴
M3	0	NC	-	NC	-	I8	I ⁴	K10	K ⁵
M4	0	NC	-	F0	F ⁰	G4	G ²	I8	I ²
N2	0	NC	-	F1	F ¹	G6	G ³	I12	I ³
K5	0	F0	F ⁰	F2	F ²	J0	J ⁰	N0	N ⁰
P1	0	F2	F ¹	F4	F ³	J2	J ¹	N2	N ¹
K6	0	F4	F ²	F6	F ⁴	J4	J ²	N4	N ²
N3	0	F6	F ³	F8	F ⁵	J6	J ³	N6	N ³
L5	0	F8	F ⁴	F9	F ⁶	J8	J ⁴	N8	N ⁴
P2	0	F10	F ⁵	F10	F ⁷	J10	J ⁵	N10	N ⁵
L6	0	F12	F ⁶	F12	F ⁸	J12	J ⁶	N12	N ⁶
R1	0	F14	F ⁷	F14	F ⁹	J14	J ⁷	N14	N ⁷
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
P3	-	TCK	-	TCK	-	TCK	-	TCK	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
T2	0	NC	-	G14	G ⁹	I6	I ³	K12	K ⁶
M5	0	NC	-	G12	G ⁸	I4	I ²	K14	K ⁷
N4	0	G14	G ⁷	G10	G ⁷	K14	K ⁷	O14	O ⁷
T3	0	G12	G ⁶	G9	G ⁶	K12	K ⁶	O12	O ⁶
R3	0	G10	G ⁵	G8	G ⁵	K10	K ⁵	O10	O ⁵
M6	0	G8	G ⁴	G6	G ⁴	K8	K ⁴	O8	O ⁴
P4	0	G6	G ³	G4	G ³	K6	K ³	O6	O ³
L7	0	G4	G ²	G2	G ²	K4	K ²	O4	O ²
N5	0	G2	G ¹	G1	G ¹	K2	K ¹	O2	O ¹
M7	0	G0	G ⁰	G0	G ⁰	K0	K ⁰	O0	O ⁰
P5	0	NC	-	NC	-	G8	G ⁴	M0	M ⁰
R4	0	NC	-	NC	-	G10	G ⁵	M4	M ¹
T4	0	NC	-	NC	-	NC	-	L0	L ⁰
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-

Ordering Information

Note: ispMACH 4000 devices are all dual marked except the slowest commercial speed grade ispMACH 4000Z devices. For example, the commercial speed grade LC4128C-5T100C is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade ispMACH 4000Z devices are marked as commercial grade only.

Conventional Packaging

ispMACH 4000ZC (Zero Power, 1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35M56C	32	1.8	3.5	csBGA	56	32	C
	LC4032ZC-5M56C	32	1.8	5	csBGA	56	32	C
	LC4032ZC-75M56C	32	1.8	7.5	csBGA	56	32	C
	LC4032ZC-35T48C	32	1.8	3.5	TQFP	48	32	C
	LC4032ZC-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032ZC-75T48C	32	1.8	7.5	TQFP	48	32	C
LC4064ZC	LC4064ZC-37M132C	64	1.8	3.7	csBGA	132	64	C
	LC4064ZC-5M132C	64	1.8	5	csBGA	132	64	C
	LC4064ZC-75M132C	64	1.8	7.5	csBGA	132	64	C
	LC4064ZC-37T100C	64	1.8	3.7	TQFP	100	64	C
	LC4064ZC-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064ZC-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064ZC-37M56C	64	1.8	3.7	csBGA	56	32	C
	LC4064ZC-5M56C	64	1.8	5	csBGA	56	32	C
	LC4064ZC-75M56C	64	1.8	7.5	csBGA	56	32	C
	LC4064ZC-37T48C	64	1.8	3.7	TQFP	48	32	C
	LC4064ZC-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064ZC-75T48C	64	1.8	7.5	TQFP	48	32	C
LC4128ZC	LC4128ZC-42M132C	128	1.8	4.2	csBGA	132	96	C
	LC4128ZC-75M132C	128	1.8	7.5	csBGA	132	96	C
	LC4128ZC-42T100C	128	1.8	4.2	TQFP	100	64	C
	LC4128ZC-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256ZC	LC4256ZC-45T176C	256	1.8	4.5	TQFP	176	128	C
	LC4256ZC-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256ZC-45M132C	256	1.8	4.5	csBGA	132	96	C
	LC4256ZC-75M132C	256	1.8	7.5	csBGA	132	96	C
	LC4256ZC-45T100C	256	1.8	4.5	TQFP	100	64	C
	LC4256ZC-75T100C	256	1.8	7.5	TQFP	100	64	C

ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5M56I	32	1.8	5	csBGA	56	32	I
	LC4032ZC-75M56I	32	1.8	7.5	csBGA	56	32	I
	LC4032ZC-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032ZC-75T48I	32	1.8	7.5	TQFP	48	32	I

ispMACH 4000C (1.8V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384C	LC4384C-5FT256I	384	1.8	5	ftBGA	256	192	I
	LC4384C-75FT256I	384	1.8	7.5	ftBGA	256	192	I
	LC4384C-10FT256I	384	1.8	10	ftBGA	256	192	I
	LC4384C-5F256I ¹	384	1.8	5	fpBGA	256	192	I
	LC4384C-75F256I ¹	384	1.8	7.5	fpBGA	256	192	I
	LC4384C-10F256I ¹	384	1.8	10	fpBGA	256	192	I
	LC4384C-5T176I	384	1.8	5	TQFP	176	128	I
	LC4384C-75T176I	384	1.8	7.5	TQFP	176	128	I
	LC4384C-10T176I	384	1.8	10	TQFP	176	128	I
LC4512C	LC4512C-5FT256I	512	1.8	5	ftBGA	256	208	I
	LC4512C-75FT256I	512	1.8	7.5	ftBGA	256	208	I
	LC4512C-10FT256I	512	1.8	10	ftBGA	256	208	I
	LC4512C-5F256I ¹	512	1.8	5	fpBGA	256	208	I
	LC4512C-75F256I ¹	512	1.8	7.5	fpBGA	256	208	I
	LC4512C-10F256I ¹	512	1.8	10	fpBGA	256	208	I
	LC4512C-5T176I	512	1.8	5	TQFP	176	128	I
	LC4512C-75T176I	512	1.8	7.5	TQFP	176	128	I
	LC4512C-10T176I	512	1.8	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-25T48C	32	2.5	2.5	TQFP	48	32	C
	LC4032B-5T48C	32	2.5	5	TQFP	48	32	C
	LC4032B-75T48C	32	2.5	7.5	TQFP	48	32	C
	LC4032B-25T44C	32	2.5	2.5	TQFP	44	30	C
	LC4032B-5T44C	32	2.5	5	TQFP	44	30	C
	LC4032B-75T44C	32	2.5	7.5	TQFP	44	30	C
LC4064B	LC4064B-25T100C	64	2.5	2.5	TQFP	100	64	C
	LC4064B-5T100C	64	2.5	5	TQFP	100	64	C
	LC4064B-75T100C	64	2.5	7.5	TQFP	100	64	C
	LC4064B-25T48C	64	2.5	2.5	TQFP	48	32	C
	LC4064B-5T48C	64	2.5	5	TQFP	48	32	C
	LC4064B-75T48C	64	2.5	7.5	TQFP	48	32	C
	LC4064B-25T44C	64	2.5	2.5	TQFP	44	30	C
	LC4064B-5T44C	64	2.5	5	TQFP	44	30	C
	LC4064B-75T44C	64	2.5	7.5	TQFP	44	30	C
LC4128B	LC4128B-27T128C	128	2.5	2.7	TQFP	128	92	C
	LC4128B-5T128C	128	2.5	5	TQFP	128	92	C
	LC4128B-75T128C	128	2.5	7.5	TQFP	128	92	C
	LC4128B-27T100C	128	2.5	2.7	TQFP	100	64	C
	LC4128B-5T100C	128	2.5	5	TQFP	100	64	C
	LC4128B-75T100C	128	2.5	7.5	TQFP	100	64	C

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C ¹	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C ¹	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C ¹	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I

Lead-Free Packaging**ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Commercial Devices**

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35MN56C	32	1.8	3.5	Lead-free csBGA	56	32	C
	LC4032ZC-5MN56C	32	1.8	5	Lead-free csBGA	56	32	C
	LC4032ZC-75MN56C	32	1.8	7.5	Lead-free csBGA	56	32	C
	LC4032ZC-35TN48C	32	1.8	3.5	Lead-free TQFP	48	32	C
	LC4032ZC-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032ZC-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
LC4064ZC	LC4064ZC-37MN132C	64	1.8	3.7	Lead-free csBGA	132	64	C
	LC4064ZC-5MN132C	64	1.8	5	Lead-free csBGA	132	64	C
	LC4064ZC-75MN132C	64	1.8	7.5	Lead-free csBGA	132	64	C
	LC4064ZC-37TN100C	64	1.8	3.7	Lead-free TQFP	100	64	C
	LC4064ZC-5TN100C	64	1.8	5	Lead-free TQFP	100	64	C
	LC4064ZC-75TN100C	64	1.8	7.5	Lead-free TQFP	100	64	C
	LC4064ZC-37MN56C	64	1.8	3.7	Lead-free csBGA	56	32	C
	LC4064ZC-5MN56C	64	1.8	5	Lead-free csBGA	56	32	C
	LC4064ZC-75MN56C	64	1.8	7.5	Lead-free csBGA	56	32	C
	LC4064ZC-37TN48C	64	1.8	3.7	Lead-free TQFP	48	32	C
	LC4064ZC-5TN48C	64	1.8	5	Lead-free TQFP	48	32	C
	LC4064ZC-75TN48C	64	1.8	7.5	Lead-free TQFP	48	32	C
LC4128ZC	LC4128ZC-42MN132C	128	1.8	4.2	Lead-free csBGA	132	96	C
	LC4128ZC-75MN132C	128	1.8	7.5	Lead-free csBGA	132	96	C
	LC4128ZC-42TN100C	128	1.8	4.2	Lead-free TQFP	100	64	C
	LC4128ZC-75TN100C	128	1.8	7.5	Lead-free TQFP	100	64	C
LC4256ZC	LC4256ZC-45TN176C	256	1.8	4.5	Lead-free TQFP	176	128	C
	LC4256ZC-75TN176C	256	1.8	7.5	Lead-free TQFP	176	128	C
	LC4256ZC-45MN132C	256	1.8	4.5	Lead-free csBGA	132	96	C
	LC4256ZC-75MN132C	256	1.8	7.5	Lead-free csBGA	132	96	C
	LC4256ZC-45TN100C	256	1.8	4.5	Lead-free TQFP	100	64	C
	LC4256ZC-75TN100C	256	1.8	7.5	Lead-free TQFP	100	64	C

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5MN56I	32	1.8	5	Lead-free csBGA	56	32	I
	LC4032ZC-75MN56I	32	1.8	7.5	Lead-free csBGA	56	32	I
	LC4032ZC-5TN48I	32	1.8	5	Lead-free TQFP	48	32	I
	LC4032ZC-75TN48I	32	1.8	7.5	Lead-free TQFP	48	32	I

ispMACH 4000V (3.3V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FTN256AI	256	3.3	5	Lead-free ftBGA	256	128	I
	LC4256V-75FTN256AI	256	3.3	7.5	Lead-free ftBGA	256	128	I
	LC4256V-10FTN256AI	256	3.3	10	Lead-free ftBGA	256	128	I
	LC4256V-5FTN256BI	256	3.3	5	Lead-free ftBGA	256	160	I
	LC4256V-75FTN256BI	256	3.3	7.5	Lead-free ftBGA	256	160	I
	LC4256V-10FTN256BI	256	3.3	10	Lead-free ftBGA	256	160	I
	LC4256V-5FN256AI ¹	256	3.3	5	Lead-free fpBGA	256	128	I
	LC4256V-75FN256AI ¹	256	3.3	7.5	Lead-free fpBGA	256	128	I
	LC4256V-10FN256AI ¹	256	3.3	10	Lead-free fpBGA	256	128	I
	LC4256V-5FN256BI ¹	256	3.3	5	Lead-free fpBGA	256	160	I
	LC4256V-75FN256BI ¹	256	3.3	7.5	Lead-free fpBGA	256	160	I
	LC4256V-10FN256BI ¹	256	3.3	10	Lead-free fpBGA	256	160	I
	LC4256V-5TN176I	256	3.3	5	Lead-free TQFP	176	128	I
	LC4256V-75TN176I	256	3.3	7.5	Lead-free TQFP	176	128	I
	LC4256V-10TN176I	256	3.3	10	Lead-free TQFP	176	128	I
	LC4256V-5TN144I	256	3.3	5	Lead-free TQFP	144	96	I
	LC4256V-75TN144I	256	3.3	7.5	Lead-free TQFP	144	96	I
	LC4256V-10TN144I	256	3.3	10	Lead-free TQFP	144	96	I
	LC4256V-5TN100I	256	3.3	5	Lead-free TQFP	100	64	I
	LC4256V-75TN100I	256	3.3	7.5	Lead-free TQFP	100	64	I
	LC4256V-10TN100I	256	3.3	10	Lead-free TQFP	100	64	I
LC4384V	LC4384V-5FTN256I	384	3.3	5	Lead-free ftBGA	256	192	I
	LC4384V-75FTN256I	384	3.3	7.5	Lead-free ftBGA	256	192	I
	LC4384V-10FTN256I	384	3.3	10	Lead-free ftBGA	256	192	I
	LC4384V-5FN256I ¹	384	3.3	5	Lead-free fpBGA	256	192	I
	LC4384V-75FN256I ¹	384	3.3	7.5	Lead-free fpBGA	256	192	I
	LC4384V-10FN256I ¹	384	3.3	10	Lead-free fpBGA	256	192	I
	LC4384V-5TN176I	384	3.3	5	Lead-free TQFP	176	128	I
	LC4384V-75TN176I	384	3.3	7.5	Lead-free TQFP	176	128	I
	LC4384V-10TN176I	384	3.3	10	Lead-free TQFP	176	128	I
LC4512V	LC4512V-5FTN256I	512	3.3	5	Lead-free ftBGA	256	208	I
	LC4512V-75FTN256I	512	3.3	7.5	Lead-free ftBGA	256	208	I
	LC4512V-10FTN256I	512	3.3	10	Lead-free ftBGA	256	208	I
	LC4512V-5FN256I ¹	512	3.3	5	Lead-free fpBGA	256	208	I
	LC4512V-75FN256I ¹	512	3.3	7.5	Lead-free fpBGA	256	208	I
	LC4512V-10FN256I ¹	512	3.3	10	Lead-free fpBGA	256	208	I
	LC4512V-5TN176I	512	3.3	5	Lead-free TQFP	176	128	I
	LC4512V-75TN176I	512	3.3	7.5	Lead-free TQFP	176	128	I
	LC4512V-10TN176I	512	3.3	10	Lead-free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

Revision History (Cont.)

Date	Version	Change Summary
January 2004	20z	ispMACH 4000Z data sheet status changed from preliminary to final. Documents production release of the ispMACH 4256Z device.
		Added new feature - ispMACH 4000Z supports operation down to 1.6V.
		Added lead-free packaging ordering part numbers for the ispMACH 4000Z/C/V devices.
April 2004	21z	Updated I_{PU} (I/O Weak Pull-up Resistor Current) max. specification for the ispMACH 4000V/B/C; -150 μ A to -200 μ A.
November 2004	22z	Added User Electronic Signature section.
		Added ispMACH 4000B (2.5V) Lead-Free Ordering Part Numbers.
December 2004	22z.1	Updated Further Information section.
February 2006	22z.2	Clarification to ispMACH 4000Z Input Leakage (I_{IH}) specification.
March 2007	22.3	Updated ispMACH 4000 Introduction section.
		Updated Signal Descriptions table.
June 2007	22.4	Updated Features bullets to include reference to "LA" automotive data sheet under the "Broad Device Offering" bullet.
		Added footnote 1 to Part Number Description to reference the "LA" automotive data sheet.
		Changed device temperature references from 'Automotive' to "Extended Temperature" for non-AEC-Q100 qualified devices.
November 2007	23.0	Added 256-ftBGA package Ordering Part Number information per PCN#14A-07.
May 2009	23.1	Correction to t_{CW} , t_{GW} , t_{WIR} and f_{MAX} parameters in ispMACH 4000Z External Switching Characteristics table.
		Correction to t_{CW} , t_{GW} , t_{WIR} and f_{MAX} parameters in ispMACH 4000V/B/C External Switching Characteristics table.